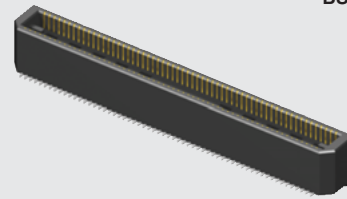


BTE-040-02-L-D-A



BTE-060-02-F-D-A

BTE, BSE SERIES

BASIC BLADE & BEAM HEADER & SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BTE or www.samtec.com?BSE

- Insulator Material:** Liquid Crystal Polymer
- Contact Material:** Phosphor Bronze
- Plating:** Au or Sn over 50µ" (1,27 µm) Ni
- Current Rating:** 2 A per pin (1 pin powered per row)
- Operating Temp Range:** -55°C to +125°C
- Voltage Rating:** 225 VAC with 5 mm Stack Height
- Max Cycles:** 100
- RoHS Compliant:** Yes

- Processing:**
- Lead-Free Solderable:** Yes
- SMT Lead Coplanarity:** (0,10 mm) .004" max (020-080) (0,15 mm) .006" max (100-120)
- Board Stacking:** For applications requiring more than two connectors per board or 80 positions or higher, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5,00) .197
-02	(8,00) .315

*Processing conditions will affect mated height.

ALSO AVAILABLE (MOQ Required)

- 30µ" (0,76 µm) Gold
 - Edge Mount Capability
 - Friction Lock option
 - 11 mm, 14 mm, 16,10 mm, 19,10 mm, 22 mm, 25 mm and 30 mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)
- Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

BTE — **NO. OF POSITIONS PER ROW** — **LEAD STYLE** — **PLATING OPTION** — **D** — **A** — **OTHER OPTION**

Mates with: **BSE**

-020, -040, -060, -080, -100, -120

Specify **LEAD STYLE** from chart

LEAD STYLE	A
-01	(4,27) .168
-02	(7,21) .284

-F = Gold Flash on contact, Matte Tin on tail

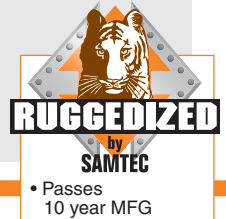
-L = 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

-C* = Electro-Polished Selective 50µ" (1,27 µm) min Au over 150µ" (3,81 µm) Ni on Signal Pins in contact area, Matte Tin over 50µ" (1,27 µm) min Ni on all solder tails

-K = (7,00 mm) .275" DIA Polyimide Film Pick & Place Pad

-TR = Tape & Reel (60 positions maximum)

*Note: -C Plating passes 10 year MFG testing



BSE — **NO. OF POSITIONS PER ROW** — **01** — **PLATING OPTION** — **D** — **A** — **OTHER OPTION**

Mates with: **BTE**

-020, -040, -060, -080, -100, -120

-F = Gold Flash on contact, Matte Tin on tail

-L = 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

-C* = Electro-Polished Selective 50µ" (1,27 µm) min Au over 150µ" (3,81 µm) Ni on Signal Pins in contact area, Matte Tin over 50µ" (1,27 µm) min Ni on all solder tails

-TR = Tape & Reel (80 positions maximum)

*Note: -C Plating passes 10 year MFG testing